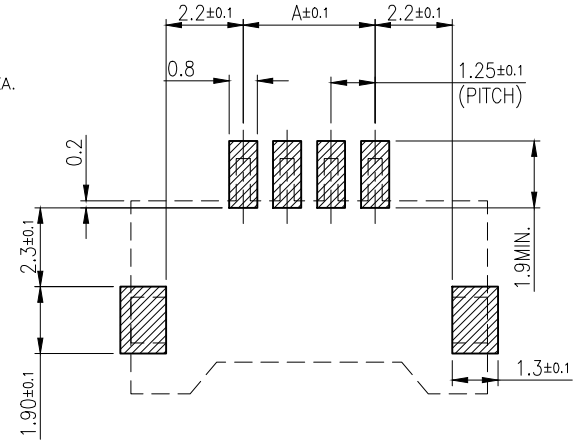


- NOTES:
1. MATERIAL:
    - 1.1 HOUSING: LCP
    - 1.2 CONTACT: COPPER ALLOY
    - 1.3 FITTING NAIL: COPPER ALLOY
  2. FINISH:
    - 2.1 CONTACT:
      - 1:GOLD FLASH PLATING ON CONTACT AND SOLDER AREA.
      - 50~100u" NICKEL UNDERPLATING OVERALL.
    - 2.2 FITTING NAIL:
      - N:100~200u" TIN PLATING ON SOLDER TAILS.
      - 50~100u" NICKEL UNDERPLATING OVERALL.
  3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
  4. SPEC. PLS. REFER TO PS-50280-XXXX
  5. PACKAGE PLS. REFER TO 88234-xxxx-P-TRP
  6. PART NUMBER

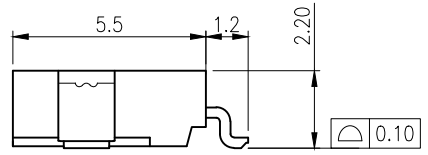
P/N LEGEND  
51414-XXX X X-XXX

NO OF CKT      COLOR  
001:BLACK




PACKING      PLATING  
O:TAPE&REEL WITHOUT MYLAR      1:G/F (LEAD FREE)  
N:MATT TIN(LEAD FREE)



RECOMMENDED P.C. BOARD PATTERN DIM. (REF.)



| CKT. | A     | B     | C     | D     |
|------|-------|-------|-------|-------|
| 10   | 11.25 | 13.77 | 17.65 | 10.00 |
| 14   | 16.25 | 18.77 | 22.65 | 15.00 |

|   |   |  |   |   |
|---|---|--|---|---|
| <b>QUALITY SYMBOLS</b><br>MAJOR <br>CRITICAL  | DRAWN BY<br>TIANYINGHONG<br>CHECKED BY<br>XUZHIYONG<br>APPROVED BY<br>XUZHIYONG | DATE<br>19/01/10<br>DATE<br>19/01/10<br>DATE<br>19/01/10 | <br><br><b>TITLE</b><br>1.25mm WIRE TO BOARD WAFER<br>LPF-2 SMT R/A TYPE |   |
| <b>GENERAL TOLERANCES<br/>(UNLESS SPECIFIED)</b><br>X. ±0.5<br>.X ±0.25<br>.XX ±0.15<br>.XXX ±0.1<br>ANGLES ±2°   | UNITS<br>mm   | SIZE<br>A4<br>REV<br>A                                   |   | RFG NO.<br>N/A<br>DWG NO.<br>51414-XXXX-XXX |
|   | SCALE<br>1:1  | SHEET NO.<br>1 OF 1                                      |   |   |
|   |   |  |   |   |